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(54) ARCHITECTURE TO PROVIDE LIQUID AND CLOSED LOOP AIR COOLING

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(57) ABSTRACT

Multiple systems and methods for providing combined liquid and air cooling for IT units are disclosed. The system includes a dry cooling section with at least one dry cooler and a liquid loop interface with at least one liquid heat exchange device. A primary loop includes at least one dry cooler of the dry cooler section, and a secondary loop includes the at least one liquid heat exchange device of the liquid loop interface that provides liquid cooling to one or more IT units. The system may include an air/liquid exchange section with at least one air/liquid exchange device that provides air cooling to the one or more IT units. The at least one air-liquid heat exchange device is part of the primary loop.

